Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2520	257/712	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 19:25
L2	2540	(257/712).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 19:22
L3	2970	257/777	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 19:43
L4	1330	257/685	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 19:57
L5	3141	257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:13
L6	0	257/E31.131	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:14
L7	1	257/E23.051	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:14
L8	2799	438/108	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:17

L9	1217	438/109	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:28
L10	3952	361/760	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:40
L11	548	361/696	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:41
L12	1681	361/697	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:47
L13	259	361/701	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:50
L14	695	361/702	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 20:54
L15	1432	361/709	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:02
L16	389	361/711	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:07

L17	30	29/888.045	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:13
L18	674	29/890.03	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:14
L19	162	29/890.032	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:21
L20	84	29/890.045	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:23
L21	61	29/895.212	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:25
L22	457	29/726	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:28
L23	51	29/726.5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/07 21:29
L24	2572	(semiconductor or chip or dice or die or IC) near operat$3 with (temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/07 21:31
L25	1390	(semiconductor or chip or dice or die or IC) near operat$3 with (temperature)	USPAT	OR	ON	2005/11/07 21:32

L26	26	(semiconductor or chip or dice or die or IC) near operat$3 with (temperature) with degree	USPAT	OR	ON	2005/11/07 21:32
S1	4	"6710461".pn. or "6624506".pn. or "6501169".pn. or "6492720".pn.	USPAT	OR	OFF	2005/11/07 19:21
S2	11993	wafer and heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer)	USPAT	OR	ON	2005/02/15 16:59
S3	4300	(semiconductor) near wafer and heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer)	USPAT	OR	ON	2005/02/15 19:03
S4	338	S3 and stack$3 with wafer	USPAT	OR	ON	2005/02/15 17:53
S5	8	"5,475,215".pn. or "5,604,377".pn. or "5,923,796".pn. or "6,097,857".pn. or "6,230,252".pn. or "6,355,976".pn. or "6,452,705".pn. or "6,611,057".pn.	USPAT	OR	ON	2005/02/15 17:55
S6	283	(semiconductor) near wafer and heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) same (coolant or liquor)	USPAT	OR	ON	2005/02/15 20:34
S7	319	S4 not S6	USPAT	OR	ON	2005/02/15 19:03
S8	264	S6 not S4	USPAT	OR	ON	2005/02/15 20:13
S9	14	"4392153"	USPAT	OR	ON	2005/02/15 20:13
S10	4	(semiconductor) near wafer and heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) same (coolant or liquor)	JPO	OR	ON	2005/02/15 20:35
S11	18	(semiconductor) near wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) with (alternat$3 or between)	JPO	OR	ON	2005/02/15 20:36
S12	113	(semiconductor) near wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) with (alternat$3 or between)	USPAT	OR	ON	2005/02/15 20:43
S13	28	(semiconductor) near wafer same heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) with (side) and (cool$4 or liquor) with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer)	USPAT	OR	ON	2005/02/15 20:44
S14	38	(semiconductor) with wafer same heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) with (side) and (cool$4 or liquor) with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer)	USPAT	OR	ON	2005/02/15 20:50

S15	66	(semiconductor) with wafer and side near heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) and (cool$4 or liquor)	USPAT	OR	ON	2005/02/15 21:08
S16	1	"6492720"	USPAT	OR	ON	2005/02/15 21:01
S17	1	"4226281".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:03
S18	1	"4235283".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:03
S19	1	"4830456".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:03
S20	1	"5348214".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:03
S21	1	"5514852".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:03
S22	1	"5661639".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:04
S23	1	"5684675".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:04
S24	1	"5811877".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:04
S25	1	"5834843".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:04
S26	1	"5898575".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:04
S27	1	"6005290".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:04
S28	1	"6115242".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:04
S29	1	"6166437".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:05
S30	1	"6226776".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:05
S31	1	"6353264".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:05
S32	1	"6404048".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:05
S33	1	"6353264".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:05
S34	0	(semiconductor) with wafer with cover$3 near side with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) and (coolant or liquor or cooling near water)	USPAT	OR	ON	2005/02/15 21:10

S35	0	cover$3 near side with (semiconductor) with wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) and (coolant or liquor or cooling near water)	USPAT	OR	ON	2005/02/15 21:10
S36	0	cover$3 near side with wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) and (coolant or liquor or cooling near water)	USPAT	OR	ON	2005/02/15 21:10
S37	64	side with wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) and (coolant or liquor or cooling near water)	USPAT	OR	ON	2005/02/15 21:14
S38	1	wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) with alternat$3 with stack$3	USPAT	OR	ON	2005/02/15 21:15
S39	74	wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) with via	USPAT	OR	ON	2005/02/15 21:17
S40	596	wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) and wafer with via	USPAT	OR	ON	2005/02/15 21:18
S41	110	wafer with heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) and wafer with via and heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer) with via	USPAT	OR	ON	2005/02/15 21:25
S42	1009	257/777 and wafer	USPAT	OR	ON	2005/02/15 21:24
S43	137	257/777 and wafer with (via or though near hole)	USPAT	OR	ON	2005/02/15 21:25
S44	50	S43 and wafer and heat near (sink or radiat$3 or dissipat$3 or spread$3 or transfer)	USPAT	OR	ON	2005/02/15 21:39
S45	77	S43 and wafer and heat	USPAT	OR	ON	2005/02/15 21:57
S46	1	"3851221".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:49
S47	1	"4103318".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:49
S48	1	"4361261".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:49
S49	1	"4444349".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:49
S50	1	"4586642".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:49

S51	1	"4730232".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:49
S52	1	"4763188".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:49
S53	1	"4982265".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:50
S54	1	"5025306".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:50
S55	1	"5040052".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:50
S56	1	"5140404".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:50
S57	1	"5172215".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:50
S58	1	"5176311".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:50
S59	1	"5177032".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:50
S60	1	"5229647".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:50
S61	1	"5291060".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:51
S62	1	"5291061".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:51
S63	1	"5323060".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:51
S64	1	"5384689".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:51
S65	1	"5432729".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:51
S66	1	"5620928".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:51
S67	1	"5682062".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:51
S68	1	"5721452".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:52
S69	1	"5739581".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:52
S70	1	"5815372".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:52
S71	1	"5872025".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:52
S72	1	"5886412".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:54
S73	0	"#PATENT#".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:54

S74	0	"#PATENT#".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:54
S75	1	"5989982".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:54
S76	0	"#PATENT#".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:54
S77	1	"6002163".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:55
S78	1	"6005778".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:55
S79	1	"6013948".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:55
S80	1	"6030855".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:55
S81	1	"RE36613".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:55
S82	1	"6033931".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:55
S83	1	"6051886".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:55
S84	1	"6057598".PN.	USPAT; USOCR	OR	OFF	2005/02/15 21:55
S85	129	"5229647"	USPAT	OR	ON	2005/02/15 21:57
S86	82	"5229647" and heat	USPAT	OR	ON	2005/02/15 21:57
S87	9	"5229647" and heat with (via or hole)	USPAT	OR	ON	2005/02/15 22:05
S88	3	"6577013" and heat with (via or hole)	USPAT	OR	ON	2005/02/15 22:07
S89	1340	wafer with (via or hole) and heat with (via or hole)	USPAT	OR	ON	2005/02/15 22:08
S90	129	S89 and stack$3 with wafer	USPAT	OR	ON	2005/02/15 22:08
S91	155	wafer with through near (via or open$3 or hole) and heat with through near (via or open$3 or hole)	USPAT	OR	ON	2005/02/16 12:18
S92	422	wafer with through with (via or open$3 or hole) and heat with through with (via or open$3 or hole)	USPAT	OR	ON	2005/02/16 12:25
S93	267	S92 not S91	USPAT	OR	ON	2005/02/16 12:18
S94	1388	wafer with (via or open$3 or hole) and heat with (via or open$3 or hole) and wafer with heat	USPAT	OR	ON	2005/02/16 12:26
S95	3	wafer with (via or open$3 or hole) and heat with (via or open$3 or hole) and wafer with heatsink	USPAT	OR	ON	2005/02/16 12:26

S96	0	wafer with (via or open$3 or hole) and heat with (via or open$3 or hole) and wafer with heatslug	USPAT	OR	ON	2005/02/16 12:26
S97	3	wafer with (via or open$3 or hole) and heat with (via or open$3 or hole) and wafer same heatsink	USPAT	OR	ON	2005/02/16 12:27
S98	170	wafer with (via or open$3 or hole) and heat with (via or open$3 or hole) and wafer same heat near sink	USPAT	OR	ON	2005/02/16 12:40
S99	1716	wafer with (via or open$3 or hole) and heat with (via or open$3 or hole) and wafer same heat	USPAT	OR	ON	2005/02/16 12:40
S100	12	wafer with (via or open$3 or hole) and heat with (via or open$3 or hole) and wafer same heat near spread$3	USPAT	OR	ON	2005/02/16 12:44
S101	1716	wafer with (via or open$3 or hole) and heat with (via or open$3 or hole) and wafer same heat	USPAT	OR	ON	2005/02/16 12:44
S102	1336	S101 not S92	USPAT	OR	ON	2005/02/16 12:44
S103	1	optical near signal with wafer with IC	USPAT	OR	ON	2005/02/16 17:46
S104	0	optical near signal same wafer with IC near optical	USPAT	OR	ON	2005/02/16 17:47
S105	8	optical near signal same (IC or integrated near circuit) near optical and wafer with (IC or integrated near circuit)	USPAT	OR	ON	2005/02/16 18:52
S106	2506	257/712	USPAT	OR	ON	2005/02/16 19:25
S107	1181	257/712	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 18:54
S108	696	257/685 and heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 20:07
S109	1598	257/686 and heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 20:07

S110	2030	361/679	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/22 07:44
S111	14	361/679 and wafer same heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:13
S112	92	(361/679 or 361/696 or 361/697 or 361/701 or 361/702 or 361/709 or 361/711) and wafer same heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:02
S113	529	361/696	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:06
S114	1570	361/697	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:08
S115	341	361/701	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:30
S116	28	(29/888.045 or 29/890.03 or 29/890.032 or 29/890.045 or 29/895.212 or 29/726 or 29/726. 5) and wafer same heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:19
S117	1	"6577013".pn. and (insulat$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:19

S118	773	361/702	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:33
S119	1461	361/709	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:46
S120	78	electrically near conductive with (crystalline near silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:40
S121	167	electrically near conductive with (gallium near arsenide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:41
S122	390	361/711	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:50
S123	62	29/888.045	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 08:54
S124	1256	29/890.03	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:03
S125	358	29/890.032	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:09

S126	179	29/890.045	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:23
S127	113	29/895.212	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:32
S128	782	29/726	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:34
S129	85	29/726.5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:52
S130	42989	wafer same heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:53
S131	29375	wafer with heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:53
S132	29375	wafers with heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 09:54
S133	459	stack$3 with wafers with heat	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 11:29

S13 4	2	"6717812".pn. or "5898575.,pn."	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 12:10
S13 5	2	"6717812".pn. or "5898575.pn."	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 16:50
S13 6	1043	(carrier or hous$3 or board or PCB) and (semiconductor or die or chip or IC) with heat and (semiconductor or die or chip or IC) with (via or hole) near through and heat with (via or hole) near through	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/22 16:52
S13 7	2857	257/777	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/15 20:52
S13 8	3024	257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/15 20:52